Newsletter

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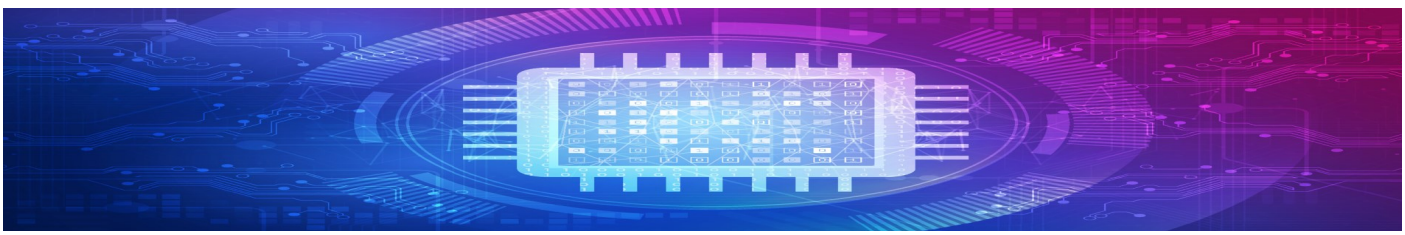
EdgeAI Webinar

Edge AI and Sensor Fusion into Smart Connected Lighting Systems

The **"Edge AI and Sensor Fusion into Smart Connected Lighting Systems"** webinar held online via Go-to-Webinar on 2nd of October 2025 and gathered 37 participants from 11 countries (Austria, Belgium, France, Germany, Greece, Italy, Latvia, Netherlands, Norway, Switzerland, Great Britain).

This webinar introduced ams OSRAM´s ambient light sensor (TCS3530) technology and its applications. The focus was on sensor fusion and integration into smart connected lighting systems via the use of different intelligence concepts for computational edge intelligence and mesh techniques. Several IoT applications (such as human-centric lighting) were highlighted, which can monitor and control indoor and outdoor spaces.

The webinar recording is available here: https://www.youtube.com/watch?v=NWmmwjnP0mk



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EdgeAI Webinar

The AI Advantage: How AI is Transforming Decarbonization, Digitalization, and the Organizations

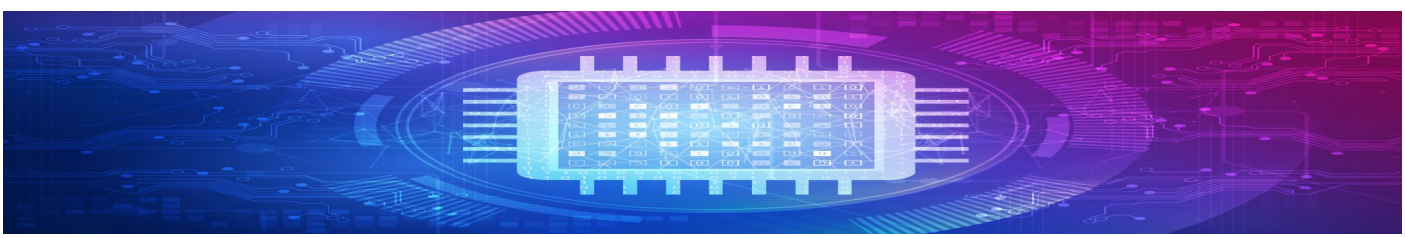
The **"The AI Advantage: How AI is Transforming Decarbonization, Digitalization, and the Organizations"** webinar held online via Go-to-Webinar on 15th of October 2025 and gathered 35 participants from 12 countries.

The webinar introduced Infineon Technologies AG's approach to decarbonization, highlighting digitalization through sensors and microcontrollers, and showcased the company's expertise in leveraging AI to drive digital transformation and sustainability. It emphasized the company's commitment to delivering innovative AI solutions.

The application of AI in real-world scenarios was discussed, including the integration of edge AI into products such as sensors and microcontrollers, further demonstrating Infineon Technologies AG's expertise in advancing digital transformation and sustainability.

A further focus was placed on building up the organization to prepare it for the challenges and opportunities associated with AI. By combining these topics, the webinar aimed to provide a comprehensive overview of the possibilities and challenges of applying AI in practice.

The webinar recording will be available here soon: https://www.youtube.com/@EdgeAI-uo8tw



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European Conference on EDGE AI

EEAI 2025 Conference, 20-22 October 2025, Naples, Italy

The **European Conference on EDGE AI Technologies and Applications – EEAI** at the Hotel San Francesco al Monte, Naples, Italy, was co-organised by the large-scale Chips JU EdgeAI project in cooperation with the CLEVER, REBECCA, TRISTAN, NEUROKIT2E, LoLiPoP IoT, SMARTY, dAIEDGE, SMARTEDGE, EdgeAI-Trust, AIMS5.0, SC4EU projects to provide a platform to exchange knowledge and ideas among experts and professionals interested in advances in AI circuits and device design, AI hardware architectures, industrial edge AI technologies, toolchains, and applications.

The conference addressed the foundations, applications, algorithms, software, communication networks, and systems related to edge AI. It showcased the latest advancements in these areas and provided a forum for debating and identifying future directions and challenges. The programme spanned three days, with a plenary session opening each day, followed by parallel sessions covering four to six topics daily.

The event welcomed representatives from academia, researchers, and industry practitioners, who exchanged insights on the latest fundamental advances in the state of the art and practice of edge AI technologies and applications. Participants also identified emerging research topics and contributed to defining the future direction of edge AI research and innovation.

The conference presentations, videos, and photos are available at: https://edge-ai-tech.eu/conference-homepage-2025/

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EFECS 2025

EFECS 2025, 3-4 December 2025, Malta

The EdgeAI project proudly showcased its work with a dedicated booth and project presentation at EFECS 2025, a key event bringing together industry leaders shaping the future of electronic components and systems.

Throughout the event, the EdgeAI project, was represented by its partners, SINTEF, ITML, EDI, Signify, Xtremion and HUA, who engaged in inspiring discussions, valuable networking, and meaningful exchanges with stakeholders from across the ecosystem.

On the final day, 4th of December, our project coordinator, Ovidiu Vermesan, delivered a detailed presentation of the project, highlighting its major outcomes, key achievements, and overall impact.

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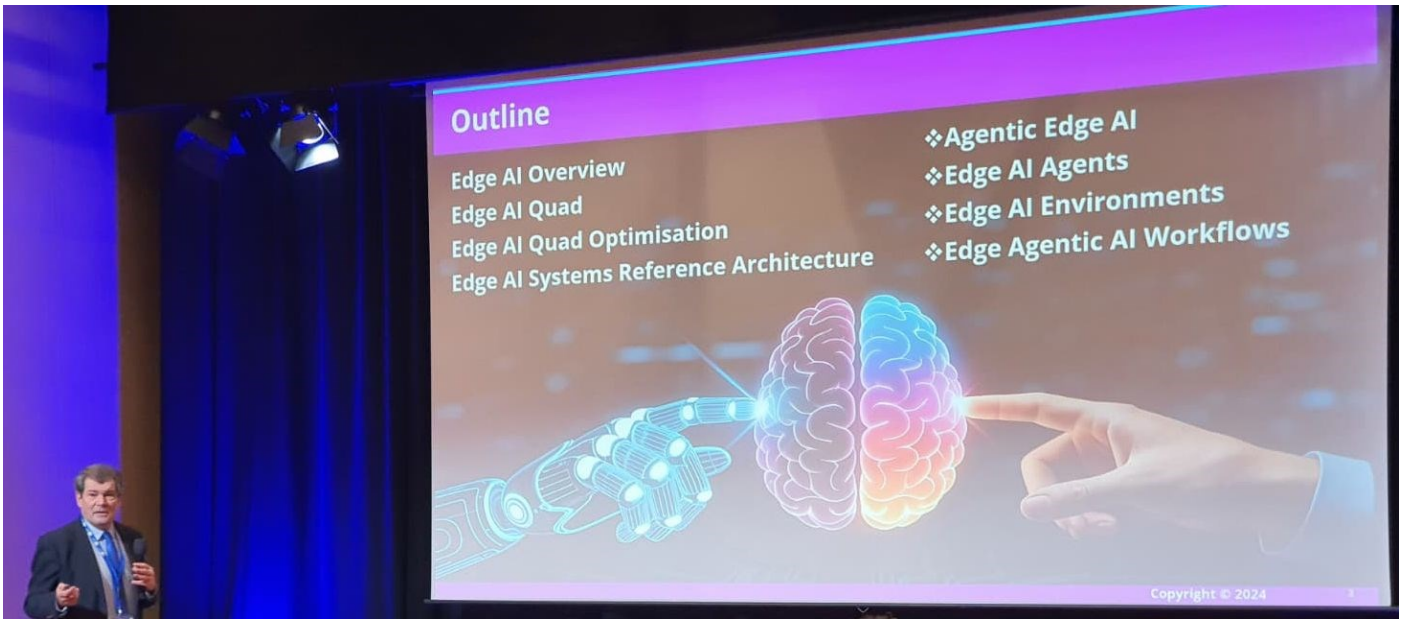
HiPEAC 2026 Conference

Workshop on The Intelligent Mesh – Edge AI Technology Roadmap for Orchestrating Autonomous Systems with Agentic and Generative AI

The **Workshop on The Intelligent Mesh – Edge AI Technology Roadmap for Orchestrating Autonomous Systems with Agentic and Generative AI** took place at the HiPEAC 2026 Conference in Kraków, Poland, on January 27, 2026. Co-organised by EdgeAI and dAIEDGE projects, this workshop provided a platform for exchanging ideas and discussing the European roadmap for the next generation of edge AI systems.



The workshop explored the future of this transformation and offered a critical forum to discuss the European roadmap for the next generation of edge AI systems. The presentations examined the foundational pillars of this evolution, ranging from novel heterogeneous hardware platforms, edge AI accelerators, and bio-inspired neuromorphic architectures to the edge AI frameworks and advanced algorithms required to power them. Key discussions focused on the rise of Small Language Models (SLMs) optimised for embedded hardware, the deployment of Vision-Language Models (VLMs) for advanced machine perception, and the transformative potential of edge generative AI.

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HiPEAC 2026 Conference

Workshop on The Intelligent Mesh – Edge AI Technology Roadmap for Orchestrating Autonomous Systems with Agentic and Generative AI

A central theme of the workshop was the emergence of agentic AI at the edge. The sessions investigated how agentic reasoning could empower individual devices and how mesh agentic AI could enable complex swarms of autonomous systems to collaborate, negotiate, and orchestrate their actions seamlessly. This advancement was identified as crucial for creating autonomous systems capable of navigating and interacting with real-world complexities, from innovative industry applications to intelligent infrastructure. This innovative educational initiative was designed for students, young researchers, and professionals eager to expand their understanding and skills in these cutting-edge technologies.

The workshop presentations are available at: https://edge-ai-tech.eu/workshops/

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https://edge-ai-tech.eu/

EdgeAI

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EdgeAI Key Facts

Start: 01 December 2022

Duration: 43 months

Budget: 35,43 M€

Coordinator: SINTEF AS

Consortium: 48 partners

Consortium

SINTEF, Infineon, ams OSRAM, SoftwareCUBE, TU Wien, imec, NXP, GNT, NEURO Controls, COGNITION FACTORY, IMST, Universität zu Lübeck, scm group, ST lite.augmented, VRANKEN POMMERY, TECHNEXT, cea, Grenoble INP UGA, Université de Reims Champagne-Ardenne, cnrs, Université Polytechnique Hauts-de-France, Χαροκοπειο Πανεπιστημιο Harokopio University, HTS High Technology Systems, Intelligent Machines IoT & Cyber Physical Systems DeepSensing S.R.L., Xtremion, Università degli Studi di Cagliari, Alma Mater Studiorum Università di Bologna, Università degli Studi di Milano, Elektronikas un datorzinātnu institūts Institute of Electronics and Computer Science, signify, Technolution, almende, TU/e, Fredrikstad energi, NxtEnergy, PROLUX, nxtech, itml innovation applied, CONVERGENCE, SynSense

Disclaimer

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